How to use the Wafer Expander / Grip / Hoop Rings

01 Connect the power cable and air tube.

02 Push the POWER and HEATER SW buttons.

03 Prepare a diced wafer.

04 Release upper and lower arms upward.

05 Set the inner ring (white) onto the stage.

06 Place the wafer on the stage.

07 Put the lower arm in downward position.

08 Secure work by turning CLAMP Switch ON.

09 Set the outer ring (black) onto the upper arm.

10 Put the upper arm in downward position.
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11. Expand wafer by turning UP/DOWN button ON. (The stage moves up to the specified height.)
Push the POWER and HEATER SW buttons.

12. Cut the film and remove the expanded wafer.
The film and wafer have been expanded and fitted to the grip ring.

Dicing street has been uniformly expanded.

13. Expanded wafer, gripped by Grip Ring
Push the UP/DOWN button.

14. Push the CLAMP button.

15. Release the lower arm and remove remaining film.
It takes about 30 seconds to complete the entire process.

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